

## N-Channel Super Junction Power MOSFET $\, \mathrm{I\!V}$

## **General Description**

The series of devices use advanced trench gate super junction technology and design to provide ultra-low Rds(ON) and low gate charge and With a rapid recovery body diode. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, industrial power applications, Fast charger, new energy vehicle charging pile, on-board OBC etc.

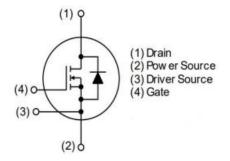
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	C	a	u	41	C	3

- New technology for high voltage device
- ●Ultra low on-resistance and ultra low conduction losses
- ●Ultra Low Gate Charge cause lower driving requirements
- Diode reverse recovery speed is super fast
- ●100% Avalanche Tested and 100% Trr Tested
- High reliability
- ●ROHS compliant

#### **Application**

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- On-board charger(OBC)

V <sub>DS min@Tjmax</sub>	710	V
R <sub>DS(ON)TYP</sub> .	21	mΩ
$I_D$	96	Α
Qg	183	nC



## ♦ Intrinsic fast-recovery body diode

Schematic diagram

V1.1

#### **Package Marking And Ordering Information**

Device	Device Package	Marking	
NCE65NF023T4	TO-247-4L	NCE65NF023T4	



Table 1. Absolute Maximum Ratings (T<sub>c</sub>=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (VGS=0V)	V <sub>DS</sub>	650	V
Gate-Source Voltage (VDS=0V) ,AC (f>1 Hz)	Vgs	±30	V
Gate-Source Voltage (VDS=0V) ,DC	Vgs	±20	V
Continuous Drain Current at Tc=25°C	I <sub>D (DC)</sub>	96	А
Continuous Drain Current at Tc=100°C	I <sub>D (DC)</sub>	67.2	А
Pulsed drain current (Note 1)	I <sub>DM (pluse)</sub>	288	А
Maximum Power Dissipation(Tc=25℃)	PD	530	W
Derate above 25°C		3.53	W/°C
Single pulse avalanche energy (Note 2)	Eas	576	mJ
Single pulse avalanche current (Note 2)	I <sub>AS</sub>	12	Α
Repetitive Avalanche energy ,t <sub>AR</sub> limited by T <sub>jmax</sub> (Note 1)	E <sub>AR</sub>	0.9	mJ





Reverse diode dv/dt, $V_{DS} \le 480 \text{ V,I}_{SD} < I_{D}$	dv/dt	50	V/ns
Drain Source voltage slope,V <sub>DS</sub> ≤480 V	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55+175	°C

#### **Table 2. Thermal Characteristic**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R <sub>thJC</sub>	0.28	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R <sub>thJA</sub>	62	°C /W

Table 3. Electrical Characteristics (TA=25°Cunless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states	•			•		
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =1mA	650			V
Zero Gate Voltage Drain Current(Tc=25℃)	I <sub>DSS</sub>	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V			15	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I <sub>DSS</sub>	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V			400	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V			±200	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS},I_{D}=3mA$	3	4	5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =48A		21	23	mΩ
Dynamic Characteristics						
Gate Resistance	Rg	F=1MHZ, D-S short		2.7		Ω
Input Capacitance	C <sub>lss</sub>	\/ -E0\/\/ -0\/		11300		pF
Output Capacitance	Coss	$V_{DS}$ =50V, $V_{GS}$ =0V, F=1MHz		386		pF
Reverse Transfer Capacitance	Crss	Γ- ΠΥΙΠΖ		57		pF
Total Gate Charge	Qg			183	193	nC
Gate-Source Charge	Q <sub>gs</sub>	\\ -400\\ I -404\\ -404\\		75.8		nC
Gate-Drain Charge	Q <sub>gd</sub>	V <sub>DS</sub> =400V,I <sub>D</sub> =48A,V <sub>GS</sub> =10V		55.2		nC
Gate plateau voltage	Vgp			7.2		V
Switching times						
Turn-on Delay Time	t <sub>d(on)</sub>			56		nS
Turn-on Rise Time	t <sub>r</sub>	V <sub>DD</sub> =380V,I <sub>D</sub> =50A,		22		nS
Turn-Off Delay Time	t <sub>d(off)</sub>	R <sub>G</sub> =3Ω,V <sub>GS</sub> =10V		166		nS
Turn-Off Fall Time	t <sub>f</sub>			11		nS
Source- Drain Diode Characteristics				•		
Source-drain current(Body Diode)	I <sub>SD</sub>	T. =25°C			96	Α
Pulsed-Source-drain current(Body Diode)	I <sub>SDM</sub>	T <sub>C</sub> =25°C			288	Α
Forward on voltage	V <sub>SD</sub>	Tj=25°C,I <sub>SD</sub> =96A,V <sub>GS</sub> =0V		1.0	1.2	V
Reverse Recovery Time	t <sub>rr</sub>			200		nS
Reverse Recovery Charge	Q <sub>rr</sub>	Tj=25°C,I <sub>F</sub> 50A,		1.2		uC
Peak reverse recovery current	I <sub>rrm</sub>	di/dt=100A/µs		12		Α

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. Tj=25°C,VDD=50V,VG=10V, R\_G=25 $\Omega$ 



### TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

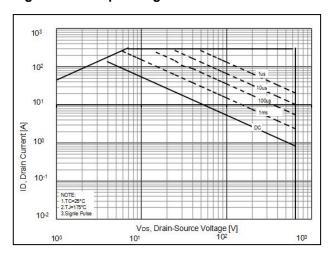


Figure 3. Output characteristics

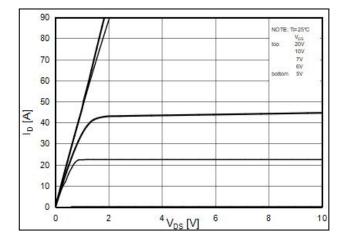


Figure 5. Static drain-source on resistance

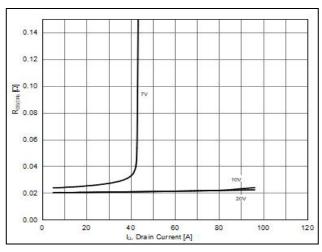


Figure 2. Source-Drain Diode Forward Voltage

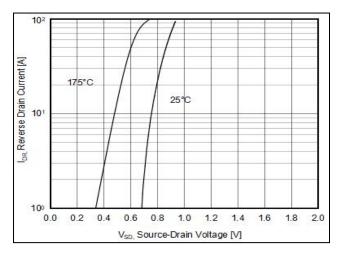


Figure 4. Transfer characteristics

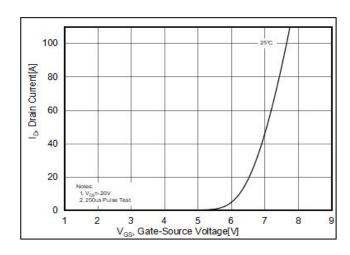


Figure 6. RDS(ON) vs Junction Temperature

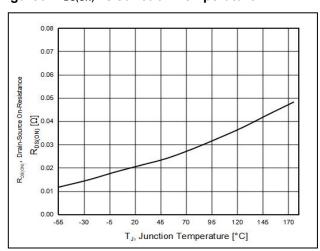




Figure 7. BV<sub>DSS</sub> vs Junction Temperature

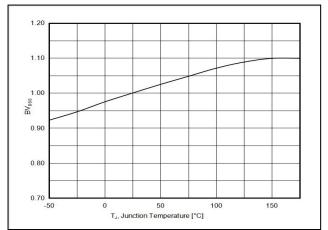


Figure 8. Maximum ID vs Junction Temperature

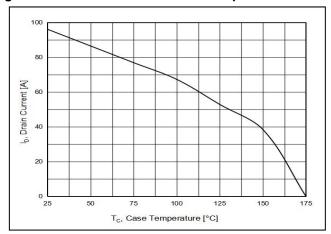


Figure 9. Gate charge waveforms

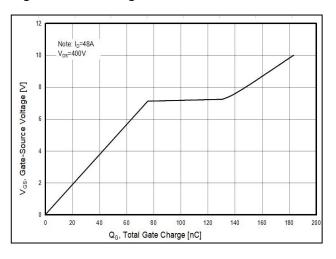


Figure 10. Capacitance

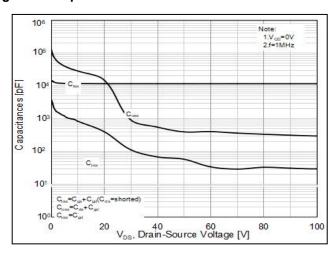
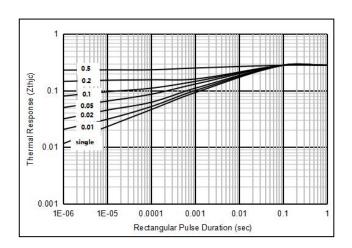


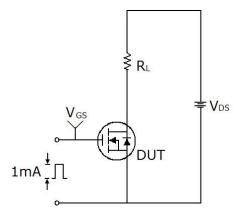
Figure 11. Transient Thermal Impedance

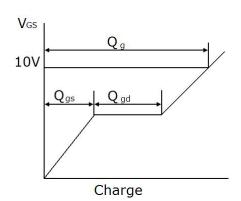




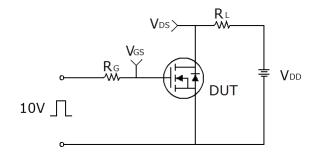
## **Test circuit**

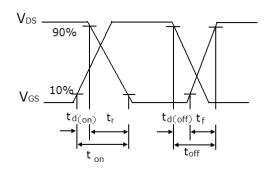
#### 1) Gate charge test circuit & Waveform



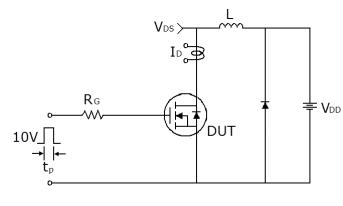


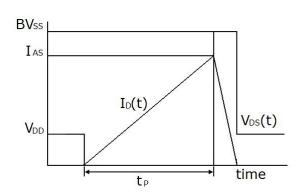
## 2) Switch Time Test Circuit:





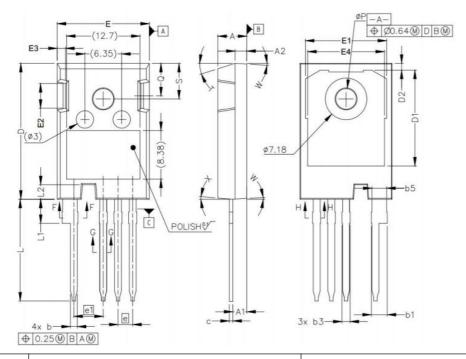
## 3) Unclamped Inductive Switching Test Circuit & Waveforms







# **TO-247-4L-B Package Information**



Cumb al	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	4.83	5.21	0.190	0.205	
A1	2.29	2.54	0.090	0.100	
A2	1.91	2.16	0.075	0.085	
b'	1.07	1.28	0.042	0.050	
b	1.07	1.33	0.042	0.052	
b1	2.39	2.94	0.094	0.116	
b2	2.39	2.84	0.094	0.112	
b3	1.07	1.60	0.042	0.063	
b4	1.07	1.50	0.042	0.059	
С	0.55	0.68	0.022	0.027	
c'	0.55	0.65	0.022	0.026	
D	23.30	23.60	0.917	0.929	
D1	16.25	17.65	0.640	0.695	
D2	0.95	1.25	0.037	0.049	
E	15.75	16.13	0.620	0.635	
E1	13.10	14.15	0.516	0.557	
E2	3.68	5.10	0.145	0.201	
E3	1.00	1.90	0.039	0.075	
E4	12.38	13.43	0.487	0.529	
L	17.31	17.82	0.681	0.702	
L1	3.97	4.37	0.156	0.172	
Q	5.49	6.00	0.216	0.236	



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